STATUS OF THE CLAIMS

The status of the claims of the present application stands as follows:

1. **(Canceled)**

2. **(Previously Presented)** An apparatus according to claim 21, wherein said rotating wafer-cleaning member comprises a brush roller having a non-filamentous cleaning surface.

3. **(Previously Presented)** An apparatus according to claim 2, wherein said brush roller comprises an electrically conductive material.

4. **(Previously Presented)** An apparatus according to claim 3, wherein said brush roller comprises a polymer filled with an electrically-conductive material.

5. **(Previously Presented)** An apparatus according to claim 4, wherein said brush roller comprises a carbon-filled perfluoroalkoxyalkane.

6. **(Canceled)**

7. **(Previously Presented)** An apparatus according to claim 3, wherein said brush roller comprises a foam rubber cleaning portion.

8. **(Canceled)**

9. **(Canceled)**

10. **(Currently Amended)** A method of removing surface contaminants from a surface of a microelectronics wafer that may have a static electrical charge thereon, comprising the steps of:

    (a) providing a microelectronics wafer having a surface; and

    (b) cleaning said surface of said microelectronics wafer with a conductive rotating wafer-cleaning member so as to remove at least some of the surface contaminants;, and

    ~~(c) during at least part of the time that step (a) is being performed, contacting said microelectronics wafer with a conductive member~~ so as to simultaneously create an

electrical ground path between said surface and an electrical ground through said conductive rotating wafer-cleaning member.

11. **(Canceled)**

12. **(Canceled)**

13. **(Canceled)**

14. **(Currently Amended)** A method according to claim 13, wherein step (~~a~~b) includes contacting said surface with an electrically conductive wafer-cleaning brush roller having a non-filamentous cleaning surface.

15. **(Canceled)**

16. **(Canceled)**

17. **(Currently Amended)** A system for removing surface contaminants from a surface, comprising:

(a) a microelectronics wafer having a surface;

(b) an electrical ground;

(~~b~~c) a wafer-cleaning region receiving said microelectronics wafer; and

(~~c~~d) a conductive rotating wafer-cleaning member operatively configured to engage said surface of microelectronics wafer in said wafer cleaning region so as to remove contaminants from said surface and provide part of a grounding path between said microelectronics wafer and said electrical ground for removing electrical charge from said microelectronics wafer~~;~~.

~~(d) an electrical ground; and~~

~~(e) an electrically conductive path extending from said microelectronics wafer to said ground.~~

18. **(Previously Presented)** A system according to claim 17, wherein said rotating wafer-cleaning member comprises a brush roller having a non-filamentous cleaning surface.

19. **(Canceled)**

20. **(Canceled)**

21. **(Currently Amended)** An apparatus for cleaning surface contaminants from a microelectronics wafer, comprising:

(a) a wafer cleaning region configured to receive a microelectronics wafer during cleaning;

(b) a conductive rotating wafer-cleaning member designed to contact the microelectronics wafer during cleaning so as to remove surface contaminants from the microelectronics wafer during cleaning; and

(c) an electrical grounding path extending from the microelectronic wafer through said conductive rotating wafer-cleaning member to an electrical ground when the apparatus is connected to the electrical ground.